
PRODUCT CHANGE NOTICE

Wafer Fabrication Process Improvement for the Listed Intersil HVSIGATE technology Products

**Refer to:
PCN12004**

Date: January 19, 2012

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To: Our Valued Intersil Customer

Subject: **Wafer Fabrication Process Improvement for the Listed Intersil HVSIGATE Technology Products** – *Intersil Palm Bay, Florida Facility*

This notice is to inform you of a pending change to the wafer fabrication process used for the listed HVSIGATE technology products. The changes implement a planarization process and affect the glassivation material composition and thickness.

- Glassivation composition and thickness changed from nitride (8kÅ) to an oxide (14kÅ) and nitride (8kÅ) stack.
- Planarization process implemented to enhance metal step coverage.

The changes will improve the long-term reliability of these products and Intersil's ability to meet customer delivery requirements. The qualification activities are complete as of the date of this notice.

Products affected:

DG401DVZ	DG408DVZ	DG411DYZ-TR5485	DG441DYZ-T
DG401DVZ-T	DG408DVZ-T	DG412DJZ	DG441DYZ-TR5485
DG401DYZ	DG408DVZ-TR5321	DG412DVZ	DG442DJZ
DG401DYZ-T	DG408DVZ-TS2568	DG412DVZ-T	DG442DVZ
DG403DVZ	DG408DYZ	DG412DVZ-TR5321	DG442DVZ-T
DG403DVZ-T	DG408DYZ-T	DG412DYZ	DG442DYZ
DG403DYZ	DG409DJZ	DG412DYZR5485	DG442DYZR5485
DG403DYZR5485	DG409DVZ	DG412DYZ-T	DG442DYZ-T
DG403DYZ-T	DG409DVZ-T	DG413DJZ	DG442DYZ-TR5485
DG403DYZ-TR5485	DG409DVZ-TR5321	DG413DVZ	DG444DVZ
DG403DYZ-TS2457	DG409DYZ	DG413DVZ-T	DG444DVZ-T
DG403W	DG409DYZ-T	DG413DYZ	DG444DYZ
DG406DJZ	DG411DJZ	DG413DYZ-T	DG444DYZR5485
DG406DYZ	DG411DVZ	DG441DJZ	DG444DYZ-T
DG406DYZ-T	DG411DVZR5485	DG441DVZ	DG444DYZ-TR5485
DG407DJZ	DG411DVZ-T	DG441DVZ-T	DG445DVZ
DG407DYZ	DG411DYZ	DG441DVZ-TR5485	DG445DVZ-T
DG407DYZ-T	DG411DYZR5485	DG441DYZ	DG445DYZ
DG408DJZ	DG411DYZ-T	DG441DYZR5485	DG445DYZ-T

The technology qualification plans for process related changes are designed using JEDEC, MIL-PRF-38535, and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. There will be no change to the product design, WAT (Wafer Acceptance Test), wafer level electrical test (circuit probe), package level electrical test, marking, or product datasheet specifications. Parts affected by this change are identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product fabricated using the improved process beginning ninety days from the date of this notification or upon depletion of existing inventory.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

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PCN12004

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PCN12004 - Qualification Summary

HVSIGATE Qualification Results (Plastic) :

STRESS	SS	hrs	Down Points	Status
HTOL	80	1000	168, 500, 1000	0/80 at 168 hrs 0/80 at 500 hrs 0/80 at 1000 hrs
PRECON L3		L3 Pb Free		Complete no failures
THB	78	1000	500, 1000	0/78 at 500 hrs 0/78 at 1000 hrs
bHAST	78	96	96	0/78 at 96 hrs Passed Stress
Temp Cycle	78	1000	500, 1000	0/78 at 500 cy 0/78 at 1000 cy Passed Stress
MRT	22	MRT11174		Level 3 Pb Free MRT11174

HVSIGATE Qualification Results (Hermetic) :

Stress	Condition	5962-9073101MEA	5962-9204201MEA
Group C	C-1	0/45 (1 lot)	0/45 (1 lots)